



501.35250CX3

#3d J. Pe. Amet
M. Brunson
8/8/02

Applicants: TANAKA et al
Serial No.: 09/904,839
Filed: July 16, 2001
For: Lead Frame And Semiconductor Device Using The
Lead Frame And Method Of Manufacturing The Same
Group: 2814
Examiner:

PRELIMINARY AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

July 24, 2002

Sir:

Prior to examination on the merits of this application, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please add the following new claims to the application.

--7. A semiconductor device comprising:

a substrate;

a semiconductor chip mounted on one surface of said substrate, said
semiconductor chip having an integrated circuit and bonding pads formed on a main
surface thereof, said main surface of said semiconductor chip having a quadrilateral
shape, said bonding pads being disposed along four sides of said main surface of
said semiconductor chip;

a plurality of conductors being disposed on said one surface of said substrate
to surround said semiconductor chip along the four sides thereof;